

View Online at https://aerobasegroup.com/nsn/5910-01-407-6627

| Body Style:  |
|--|
| Chip type  |
| Reliability Indicator:   |
| Established  |
| Reliability Failure Rate Level In Percent:   |
| 0.001  |
| Terminal Length:   |
| 0.010 inches   |
| Body Length:   |
| Between 0.065 inches and 0.095 inches  |
| Body Width:  |
| Between 0.035 inches and 0.065 inches  |
| Body Height:   |
| Between 0.022 inches and 0.055 inches  |
| Schematic Diagram Designator:  |
| No common or grounded electrode (s)  |
| Insulation Resistance At Maximum Operating Temp:   |
| 10000.0 megohms  |
| Capacitance Value Per Section:   |
| 10.000 picofarads single section   |
| Voltage Tempurature Limits Per Section In Percent Capacitance Change:  |
| -15.0/+15.0 with rated voltage applied single section  |
| Nonderated Operating Temp:   |
| Between -55.0 degrees celsius and 125.0 degrees celsius  |
| Nonderated Continuous Voltage Rating And Type Per Section:   |
| 100.0 dc single section  |
| Tolerance Range Per Section:   |
| -1.00/+1.00 percent single section   |
| Case Material:   |
| Ceramic  |
| Insulation Resistance At Reference Temp:   |
| 100000.0 megohms   |
| Dissipation Factor At Reference Tempurature In Percent:  |
| 2.500  |
| Terminal Surface Treatment:  |
| Solder   |
| Test Data Document:  |
| Mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; |
| excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmenta       |
| and performance requirements and test conditions that are shown as "typical", "average", "", etc.).  |
| Terminal Type And Quantity:  |
| 2 bonding pad  |

Specification Data:

Mil-c-55681/1 government specification



Shelf Life:

N/a

Unit Of Measure:

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Demilitarization:

No

Fiig:

A010b0

Mil-std (military Standard):

Mil-c-55681 spec.